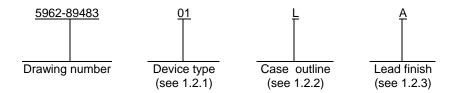
						F	KE VISI	ONS										
LTR			[DESCR	IPTIO	N					DA	ATE (YI	R-MO-I	DA)		APPI	ROVED)
А	Change total supply voltage in 1.3. Change in table I; output voltage test limits, clock to center frequency ratio, with conditions sides A, B pin 17 high, also side D pin 17 high, test limits, Q accuracy test limit Add clock to center frequency, side-to-side matching test. Change voltage test conditions and limits. Change power supply current test and limits. Change subgroups for output voltage swing in table I an and D end-point electricals in table II. Editorial changes throughout				B, C, and ts. dc offs st condi d grou	et tions		•)3-23	,		M. A	. FRYE	:				
В	For f _{CLK} /f _O , Q _{ACC} , f _O vs f _O tests under Table I, delete subgroups 7, 8A, 8B and substitute 1, 2, 3. For V _{OS1} , V _{OS2} , V _{OS3} tests under table I, delete subgroups 4, 5, 6 and substitute 1, 2, 3. Add subgroups 7, 8A, and 8B to paragraph 4.3.1. Delete subgroups 7, 8A, and 8B from Table II. Changes in accordance with N.O.R. 5962-R017-93.							В		92-12-15 N			M. A	. FRYE	<u> </u>			
С		For the total supply voltage specified under paragraph 1.3, delete and substitute 16.0 V dc. Changes in accordance with N.O.R. 59										95-0	06-02			M. A	. FRYE	<u> </u>
D	For the I _{CC} te Changes in ac						mA an	d subst	itute 23	3 mA.		96-0)4-16			M. A	. FRYE	
Е	Drawing upda	ted to reflec	ct curre	nt requi	iremen	ts. Red	drawn.	- ro				08-0	7-08			R. H	IEBER	
THE ORIGINAL REV SHEET REV	L FIRST SHEET	OF THIS D	RAWIN	IG HAS	BEEN	REPL	ACED.											
REV SHEET REV SHEET				IG HAS														
REV SHEET REV		OF THIS D		IG HAS	BEEN	E	ACED.	E	E	E	E	E	E	E				
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A		RE\ SHE PRE JOS	/ EET PAREC	D BY A. KERI	E 1				5	6 EFEN	7 SE SI	8 UPPL	9 Y CE	10			sus	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A		REV SHE PRE JOS CHE	/ EET PAREC SEPH / CKED ARLES	D BY A. KERI BY S E. BES	E 1	E	E	E	5	6 EFEN	7 SE SI	8 UPPL IBUS,	9 Y CE	10	218-3		BUS	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DRA THIS DRAWII FOR U DEPA AND AGEI	NDARD DCIRCUIT AWING NG IS AVAILABLISE BY ALL RTMENTS NCIES OF THE	REV SHE PRE JOS CHE CH APP CH	/ EET PAREC SEPH /	D BY A. KERI BY G E. BES D BY G REUS	E 1 BY SORE	E 2	E	E 4	5	efen CC	SE SI DLUM http	8 UPPL IBUS, 0://ww	y CE, OHK	NTER D 432 cc.dla	218-3 a.mil	990 JAD,	BUS	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DRA THIS DRAWII FOR U DEPA AND AGE DEPARTMEN	NDARD DCIRCUIT AWING NG IS AVAILABLISE BY ALL RTMENTS	REV SHE PRE JOS CHE CH APP CH DRA	/ EET PAREC SEPH / CKED ARLES ROVEC	D BY A. KERI BY G E. BES D BY G REUS APPRO	E 1 BY SORE JUNG DVAL D 0-30	E 2	E	E 4 MIC UNI MO	DI DI CROC	6 EFEN CO	SE SI DLUM http	BUPPLIBUS, DELINE A BICON	y CE, OHK	NTER D 432 cc.dla	218-3 a.mil S, QL BLO	990 JAD,		

DSCC FORM 2233 APR 97

1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
 - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type Generic number Circuit function

O1 LTC1064 CMOS, quad, universal filter building block

1.2.2 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
1	GDIP3-T24 or CDIP4-T24	24	Dual-in-line

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings.

Total supply voltage (+V _S to -V _S)	16.0 V dc
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+300°C
Power dissipation (PD)	500 mW
Junction temperature (T _J)	+175°C
Thermal resistance, junction-to-case (θ _{JC})	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θJA)	60°C/W

1.4 Recommended operating conditions.

Supply voltage (±V _S)	±5 V dc
Operating supply voltage range	± 2.37 V dc to ± 8.0 V dc
Ambient operating temperature range (T _A)	-55°C to +125°C

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89483
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2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at http://assist.daps.dla.mil/quicksearch/ or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
 - 3.2.1 Case outline. The case outline shall be in accordance with 1.2.2 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
 - 3.2.3 Block diagram. The block diagram shall be as specified on figure 2.
 - 3.2.4 Equivalent input offsets. The equivalent input offsets shall be as specified on figure 3.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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Test	Symbol	Conditions $-55^{\circ}C \le T_{A} \le +125^{\circ}C$ $V_{S} = \pm 5.0 \text{ V}$	Group A subgroups	Device type	Liı	mits	Unit	
		unless otherwise specified		,,	Min	Max		
Internal operational amplifiers	}			•		•		
Output voltage swings	Vout	R _L = 5.0 kΩ	4	01	-3.2	+3.2	V	
			5,6		-3.1	+3.1		
Complete filter (TTL clock inp	put level, un	less otherwise specified)	·					
Clock to center frequency ratio	fCLK / fo	Sides A, B, and C = mode 1, R1 = R3 = $50 \text{ k}\Omega$, R2 = $5.0 \text{ k}\Omega$, f _{CLK} = 1.0 MHz , Q = 10 , f _O = 20 kHz , pin 17 high, (condition A)	1,2,3,	01	01	49.6	50.4	
		Side D = mode 3, R1 = R3 = $50 \text{ k}\Omega$, R2 = R4 = $5.0 \text{ k}\Omega$, f_{CLK} = 1.0 MHz , Q = 10 , f_{O} = 20 kHz , pin 17 high , (condition B)			49.55	100.8		
		Sides A, B, and C = mode 1, R1 = R3 = $50 \text{ k}\Omega$, R2 = $5.0 \text{ k}\Omega$, fCLK = 1.0 MHz , Q = 10 , fO = 10 kHz , pin 17 low , (condition C)			99.2			
	Side D = mode 3, R1 = R3 = $50 \text{ k}\Omega$, R2 = R4 = $5.0 \text{ k}\Omega$, f _{CLK} = 1.0 MHz , Q = 10 , f _O = 10 kHz , pin 17 low, (condition D)			99.1	100.9			

	TABLE	Electrical performance chara	acteristics – co	ntinued.			
Test	Symbol	Conditions $-55^{\circ}C \le T_A \le +125^{\circ}C$	Group A subgroups	Device type	Lir	nits	Unit
		$V_S = \pm 5.0 \text{ V}$ unless otherwise specified	- casg.caps	туре	Min	Max	-
Complete filter (TTL clock in	out level, un	less otherwise specified) - Cor	ntinued.				
Q accuracy	Q _{ACC}	Sides A, B, and C = mode 1, f _{CLK} = 1.0 MHz, Q = 10	1,2,3	01	-6.0	6.0	%
		Side D = mode 3, f _{CLK} = 1.0 MHz, Q = 10			-8.0	8.0	
Clock to center frequency ratio; side-to-side matching	f _O vs	f _{CLK} / f _O conditions A through D.	1,2,3	01	-1.0	1.0	%
DC offset voltage	V _{OS1}	f _{CLK} /f _O = 50:1, f _{CLK} = 1.0 MHz, see figure 3	1,2,3	01	-15	15	mV
	V _{OS2}	f _{CLK} /f _O = 50:1 and 100:1,			-45	45	
	V _{OS3}	f _{CLK} = 1.0 MHz, see figure 3			-45	45	
Power supply current	Icc	V _S = ±5.0 V	1	01		23	mA
			2,3			26	

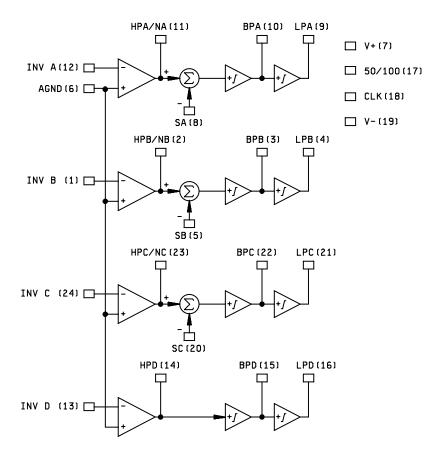
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark</u>. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
 - 3.8 Notification of change. Notification of change to DSCC-VA shall be required for any change that affects this drawing.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

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Device type	01
Case outline	L
Terminal number	Terminal symbol
1	INV B
2	HPB / NB
3	BPB
4	LPB
5	SB
6	AGND
7	+V _S
8	SA
9	LPA
10	BPA
11	HPA / NA
12	INV A
13	INV D
14	HPD
15	BPD
16	LPD
17	50 / 100
18	CLK
19	-Vs
20	SC
21	LPC
22	BPC
23	HPC / NC
24	INV C
•	

FIGURE 1. <u>Terminal connections</u>.

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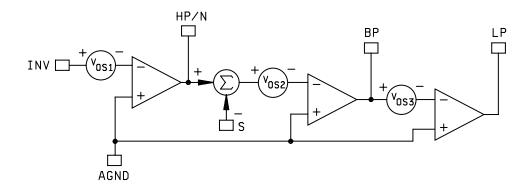


Operational notes.

- 1. By tying pin 17 to V+, all sections operate with $(f_{CLK} / f_O) = (50:1)$.
- 2. By tying pin 17 to V-, all sections operate with $(f_{CLK} / f_O) = (100:1)$.
- 3. By tying pin 17 to AGND, sections B and C operate with $(f_{CLK}/f_O) = (50:1)$ and sections A and D operate at (100:1).

FIGURE 2. Block diagram.

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NOTE: This represents one quarter of the filter building block.

FIGURE 3. Equivalent input offsets.

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4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition C. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8A, 8B, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition C. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - (2) $T_A = +125$ °C, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*,2,3,4,5,6
Group A test requirements (method 5005)	1,2,3,4,5,6
Groups C and D end-point electrical parameters (method 5005)	1,4

^{*} PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0547.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 08-07-08

Approved sources of supply for SMD 5962-89483 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DSCC maintains an online database of all current sources of supply at http://www.dscc.dla.mil/Programs/Smcr/.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-8948301LA	<u>3</u> /	LTC1064MJ/883

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply. The last known supplier is listed below.

Vendor CAGEVendor namenumberand address

64155

Linear Technology Corporation 1630 McCarthy Blvd. Milpitas, CA 95035-7417

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.